2SA1128

Silicon PNP epitaxial planar type

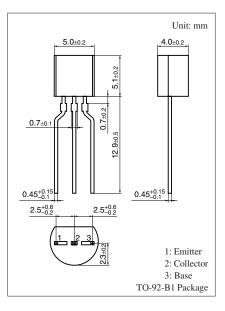
For low-frequency output amplification

Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Optimum for low-voltage operation and for converter circuits.

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-25	V	
Collector-emitter voltage (Base open)	V _{CEO}	-20	V	
Emitter-base voltage (Collector open)	V _{EBO}	-7	V	
Collector current	I _C	- 0.5	А	
Peak collector current	I _{CP}	-1	А	
Collector power dissipation	P _C	0.6	W	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	





Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

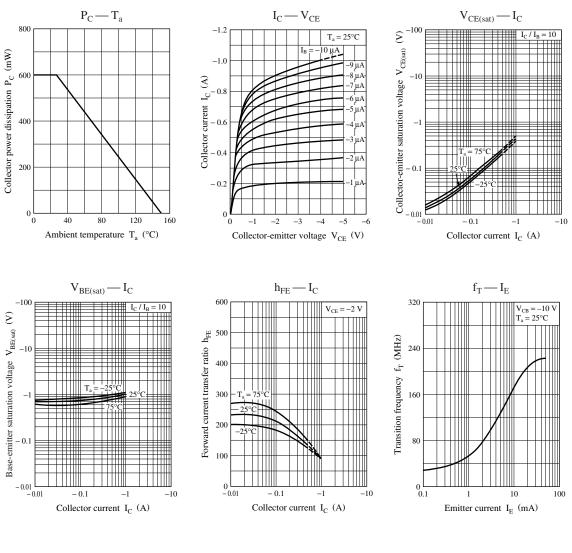
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$	-25			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-20			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = -10 \ \mu A, \ I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -25 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -20 \text{ V}, I_B = 0$			-1	μΑ
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -2 V, I_C = -0.5 A$	90		220	—
	h _{FE2}	$V_{CE} = -2 V, I_C = -1 A$	25			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -500 \text{ mA}, I_{\rm B} = -50 \text{ mA}$			- 0.4	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{\rm C} = -500 \text{ mA}, I_{\rm B} = -50 \text{ mA}$			-1.2	V
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		15	25	pF
(Common base, input open circuited)						

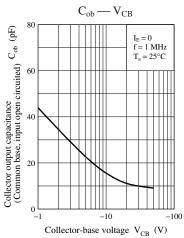
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	R
h _{FE1}	90 to 155	130 to 220

Panasonic





2

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